

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AIKO YOSHIDA	12/15/2014
MASATO TANAKA	12/15/2014
RECEIVING PARTY DATA	
Name:	SONY CORPORATION
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City:	TOKYO
State/Country:	JAPAN
Postal Code:	108-0075
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14560476
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ATTORNEY DOCKET NUMBER:	428203US8
NAME OF SUBMITTER:	SANTIAGO VILLALOBOS
SIGNATURE:	/Santiago Villalobos/
DATE SIGNED:	02/02/2016
Total Attachments: 2	
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source=428203USASSIG#page2.tif	

Docket Number: 428203US8
SOMC-SONY

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

ANTENNA-EQUIPPED CONNECTOR

For which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Mobile Communications, Inc., a Japanese corporation with offices at 1-8-15, Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as "ASSIGNEE SMC") is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1, Konan, Minato-ku, Tokyo 108-0075, Japan (hereinafter referenced as "ASSIGNEE SONY") is desirous of acquiring all the interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries held by ASSIGNEE SMC as the sole owner to the rights by this assignment ;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE SMC, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto; and

CONCURRENTLY HERewith in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNEE SMC by these presents do hereby assign, sell and transfer unto the said ASSIGNEE SONY, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto,

The undersigned inventor(s) and ASSIGNEE SMC hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE SONY, as the assignee of the whole right, title and interest thereto;

The undersigned inventor(s) and ASSIGNEE SMC further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE SONY or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

The undersigned inventor(s) and ASSIGNEE SMC further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

The undersigned inventor(s) and ASSIGNEE SMC further agree that ASSIGNEE SONY will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention

and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

The undersigned inventor(s) and ASSIGNEE SMC hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And we hereby authorize and request my attorney(s) of record in this application to insert the application number

14/560,476

Filing Date: December 4, 2014

This assignment executed on the dates indicated below.

Aiko YOSHIDA

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Aiko Yoshida

15 Dec., 2014

Signature of first or sole inventor

Date of this assignment

Masato TANAKA

Name of second inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of second inventor

Masato Tanaka

15 Dec., 2014

Signature of second inventor

Date of this assignment

SONY MOBILE COMMUNICATIONS, INC.

Date: Dec. 17, 2014 By:

Name:

HIROSHI DATE

Title:

Senior Manager, IPR Sec.